



Technical Datasheet  
Conductive Epoxy Primer

# PUMANTISTAT PRIMER

## DESCRIPTION

Pumantistat Primer is a low viscosity, high solids epoxy primer used to seal and prime concrete or other substrates prior to the application of Pumaflor Anti-static resin systems.

Pumantistat Primer is absorbed into the substrate sealing off surface defects which may cause bubbling or interference within the final surface finish. Additionally, Pumantistat Primer is intended to maintain a fully conductive bond between anti-static finishes and the substrate, by both "through" and linear conductivity. Pumantistat Primer is compatible with and adheres to an extensive range of epoxy resin and polyurethane flooring systems but is specifically intended for pre-treatment prior to application of anti-static products.

## COMPOSITION

Pumantistat Primer is an epoxy amine resin system containing a limited addition of high flash point solvent being additionally filled with conductive fillers and aggregates including carbon, ultimately producing a black finish.

## BOND STRENGTH

Pumantistat Primer applied to correctly prepared substrates exhibits bond strengths in excess to concrete and typically failure occurs within the concrete rather than the epoxy primer or overlying resin system.

## THICKNESS

150-190µm depending upon porosity and profile of substrate.

## TYPICAL INSTALLATIONS

Pumantistat Primer is used as a primer with the following Pumaflor flooring systems:-

Pumantistat 2000 Anti-static Flow  
Pumantistat H.F. Heavy duty anti-static polyurethane flooring  
Pumantistat M.D. Anti-static flow applied polyurethane flooring  
Pumantistat S.R. Anti-static slip resistant polyurethane flooring  
Pumantistat Primer may also be used as a conductive or anti-static finish in its own right.

## SUBSTRATES

Pumantistat Primer adheres to concrete, metal, wood and most synthetic flooring composites.

## SURFACE PREPARATION

To be assured of maximum adhesion and properties from Resdev resin products, the correct surface preparation is essential. Please refer to technical data sheet "Surface Preparation" reference TD102.

## EARTHING PROCEDURE

Providing the substrate has intimate contact with underlying ground, no additional earthing requirements will be needed. However, in the instance of raised or insulated floor levels a network of copper strips should be affixed to the blasted floor surface prior to priming with the Pumantistat Primer product. The copper strip network should finally be secured and bonded to a main earthing frame system.

## MIXING

Ensure that minor settlement within the resin component has been fully re-mixed to form a homogeneous product prior to mixing of the two components. Pour and drain the full contents of the hardener container into the resin container and mix the two liquids thoroughly with a slow speed electric stirrer or by hand for a minimum of two minutes or until such time as a homogeneous consistency is achieved. Special attention should be paid to scraping the sides and base of the mixing vessel.

## APPLICATION TECHNIQUES

Apply by brush or roller, working the resin system well into the floor surface. On porous surfaces apply further resin until the surface is completely wetted out. Push the resin as thinly as possible, leaving enough resin on the surface to maintain a wet appearance. Allow to cure to a hard finish before application of the appropriate finishing system. Do not allow longer than 48 hours between successive applications.

## COVERAGE RATES

Rough porous concrete	-	250g/m <sup>2</sup>
Average finish	-	220g/m <sup>2</sup>
Smooth finish	-	100g/m <sup>2</sup>

## SPECIFICATION DETAIL

Apply Pumantistat Primer to prepared surface at a typical spreading rate of 220g/m<sup>2</sup>, and allow to cure hard for a maximum period of 48 hours. Apply subsequent flooring system.

## CURE SCHEDULE

Pot Life @ 20°C	-	35-45 mins
Pot Life @ 10°C	-	60-75 mins
Hard Dry @ 20°C	-	16-24 hours
Hard Dry @ 10°C	-	24-36 hours
Full Cure @ 20°C	-	5-7 days

## CHEMICAL RESISTANCE

Please refer to technical data sheet reference TD112.

## TECHNICAL DATA

Bond Strength BS 6319	-	40N/mm <sup>2</sup> typical
Compressive Strength	-	48-52N/mm <sup>2</sup>
Flexural Strength	-	43-48N/mm <sup>2</sup>
Mixed viscosity @ 20°C	-	3.0-5.0 poise
Conductivity to BS 2050	-	Less than 0.05—100mega Ohms

## HEALTH AND SAFETY

Please read technical data sheet reference TD103 and specific health and safety data for this product provided in compliance with the requirements of EC Directive 91/155.

## STORAGE, MIXING & APPLICATION

The storage, mixing and application conditions can affect and specific health and safety data for this product provided in compliance with the requirements of EC Directive 91/155.

## TECHNICAL ADVICE

For further information on this or any other Resdev product, please contact our Customer Care Department on 01422 379131.